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June 2014

FDMD82100L

Dual N-Channel PowerTrench[®] MOSFET 100 V, 24 A, 19.5 m Ω

Features

- Max $r_{DS(on)}$ = 19.5 m Ω at V_{GS} = 10 V, I_D = 7 A
- Max $r_{DS(on)}$ = 30 m Ω at V_{GS} = 4.5 V, I_D = 5.7 A
- Ideal for flexible layout in primary side of bridge topology
- Termination is Lead-free and RoHS Compliant
- 100% UIL tested
- Kelvin High Side MOSFET drive pin-out capability

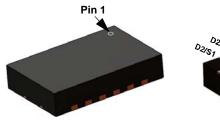


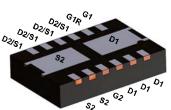
General Description

This device includes two 100V N-Channel MOSFETs in a dual Power (3.3 mm X 5 mm) package. HS source and LS Drain internally connected for half/full bridge, low source inductance package, low $r_{DS(on)}/Qg$ FOM silicon.

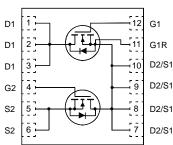
Applications

- Synchronous Buck : Primary Switch of Half / Full bridge converter for telecom
- Motor Bridge: Primary Switch of Half / Full bridge converter for BLDC motor
- MV POL: 48V Synchronous Buck Switch





Solve $\frac{1}{2}$ Solve $\frac{1}{2$



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Paramo		Ratings	Units	
V _{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _C = 25 °C		24	
I _D	-Continuous	T _A = 25 °C	(Note 1a)	7	Α
	-Pulsed	T _A = 25 °C	(Note 4)	80	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	150	mJ
	Power Dissipation	T _C = 25 °C		38	
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.1	W
	Power Dissipation	T _A = 25 °C	(Note 1b)	1	
T _J , T _{STG}	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.3	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	60	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	130	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
82100L	FDMD82100L	Power 3.3 x 5	13 "	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV_DSS	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		70		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.7	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-6		mV/°C
		V _{GS} = 10 V, I _D = 7 A		13.5	19.5	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 5.7 \text{ A}$		17.9	30	mΩ
,		$V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}, T_J = 125 ^{\circ}\text{C}$		25	36	
9 _{FS}	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_{D} = 7 \text{ A}$		29		S

Dynamic Characteristics

C _{iss}	Input Capacitance	.,		1130	1585	pF
C _{oss}	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1 MHz		173	245	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12		8.1	15	pF
R_g	Gate Resistance		0.1	1.8	3.6	Ω

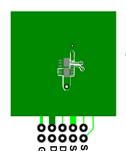
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		7.9	16	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 7 A	2.8	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	21	34	ns
t _f	Fall Time		2.9	10	ns
0	Total Gate Charge	V _{GS} = 0 V to 10 V	17	24	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 50 \text{ V}$	8	12	nC
Q_{gs}	Gate to Source Charge	I _D = 7 A	3		nC
Q_{gd}	Gate to Drain "Miller" Charge		2.3		nC

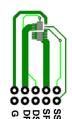
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 7 \text{ A}$ (Not	te 2)	8.0	1.2	V
t _{rr}	Reverse Recovery Time	$I_{\rm E} = 7$ A, di/dt = 100 A/µs		42	67	ns
Q _{rr}	Reverse Recovery Charge	$I_F = I A$, $ui/ui = 100 A/\mu S$		39	62	nC

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,1C} is determined by the user's board design.



a. 60 °C/W when mounted on a 1 in 2 pad of 2 oz copper



b. 130 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0 %. 3. E_{AS} of 150 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 10 A, V_{DD} = 90 V, V_{GS} = 10 V. 100% tested at L = 0.1 mH, I_{AS} = 31 A. 4. Pulse Id refers to Figure.11 Forward Bias Safe Operation Area.

Typical Characteristics (N-Channel) T_J = 25 °C unless otherwise noted

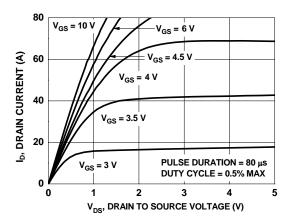


Figure 1. On Region Characteristics

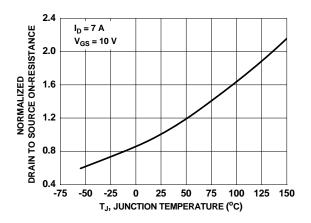


Figure 3. Normalized On Resistance vs Junction Temperature

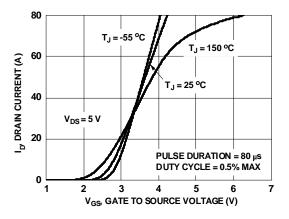


Figure 5. Transfer Characteristics

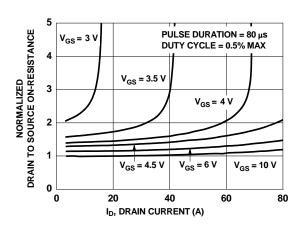


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

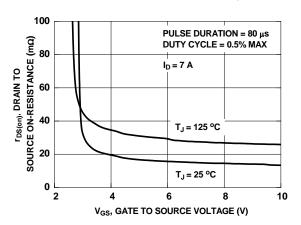


Figure 4. On-Resistance vs Gate to Source Voltage

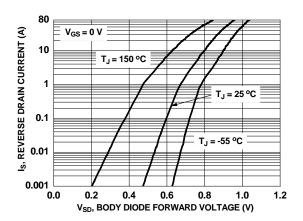


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (N-Channel) T_J = 25 °C unless otherwise noted

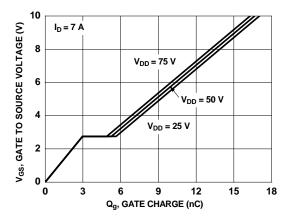


Figure 7. Gate Charge Characteristics

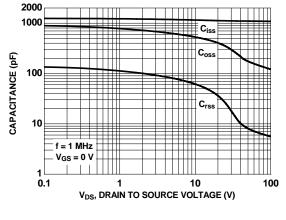


Figure 8. Capacitance vs Drain to Source Voltage

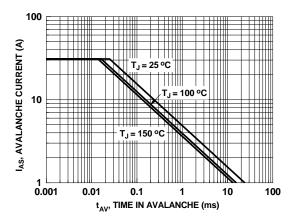


Figure 9. Unclamped Inductive Switching Capability

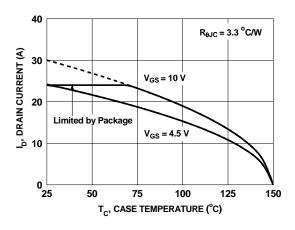


Figure 10. Maximum Continuous Drain Current vs Case Temperature

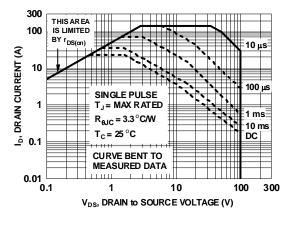


Figure 11. Forward Bias Safe Operating Area

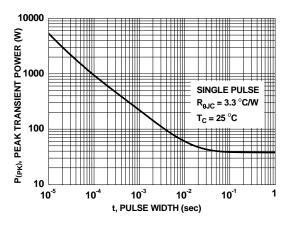


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics (N-Channel) T_J = 25 °C unless otherwise noted

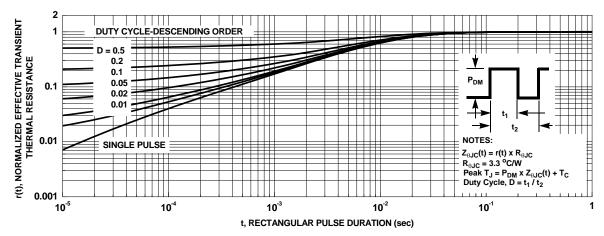
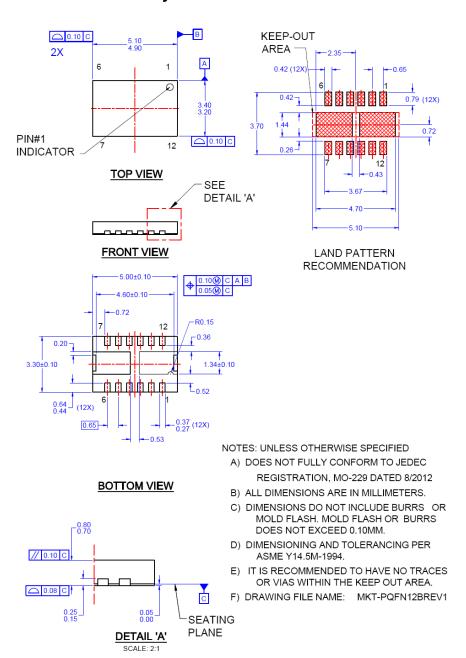


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Dimensional Outline and Pad Layout



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